

# APPLICATION DATA SHEET

Electronic Version 0.0.11

Stylesheet Version: 1.0

Attorney Docket Number: NAUP0482USA

Publication Filing Type: new-utility

Application Type: utility

Title of Invention: SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR  
MEMORY DEVICE

Customer Number Attorney: 027765



Customer Number Correspondence Address: 027765



## INVENTOR(s):

Primary Citizenship: R.O.C.  
Given Name: Kuo-Ming  
Family Name: Chen  
Residence City: Hsin-Chu Hsien  
Residence Country: TW  
Address: No. 16-1, Ta-Lin Tsun, Pei-Pu Hsiang, Hsin-Chu Hsien,  
Taiwan, R.O.C.  
Hsin-Chu Hsien , TW

Primary Citizenship: R.O.C.  
Given Name: Hung-Min  
Family Name: Liu  
Residence City: Hsin-Chu City  
Residence Country: TW  
Address: 4F, No. 30, Lane 81, Ta-Hsueh Rd., Hsin-Chu City,  
Taiwan, R.O.C.  
Hsin-Chu City , TW

